L Number	Hits	Search Text	DB	Time stamp
1	1146472	test\$3	USPAT;	2004/09/20 08:49
-			US-PGPUB;	
			ЛРО	
2	236331	wafer\$1	USPAT;	2004/09/20 08:49
	230331	Action 1	US-PGPUB;	200 1/0 2/20 00:15
			JPO	
3	722606	die or chip\$1 or dice	USPAT;	2004/09/20 08:49
	,22000	are or empty of aree	US-PGPUB;	2004/07/20 00.47
			JPO	
4	1122235	semiconduct\$3 or silicon	USPAT;	2004/09/20 08:50
•	1122233	Semiconductor of Sincon	US-PGPUB;	200-705720 00.50
			ло ЛРО	
5	2394256	contact\$1 or pad\$1	USPAT;	2004/09/20 08:51
	2374230	contactor or pager	US-PGPUB;	2004/03/20 08.31
			の5-FGF 0B, アO	İ
6	9362	bus\$2 near2 conduct\$4		2004/00/20 08.51
U	9302	busip2 liear2 conductiv4	USPAT;	2004/09/20 08:51
			US-PGPUB; JPO	
7	7626	(wafer\$1 near2 level) or wafer-level	USPAT;	2004/09/20 08:51
\	7020	(water \$1 flear 2 fever) of water-level	US-PGPUB;	2004/09/20 08:31
			JPO	
8	24373	redistribut\$3	USPAT;	2004/09/20 08:52
°	24373	Teulsulbutup3		2004/09/20 08.32
			US-PGPUB; JPO	
9	135122	(die or chip\$1 or dice) with (semiconduct\$3 or silicon))	2004/00/20 09:52
	133122	(die of chips) of dice) with (semiconducts) of shicon)	USPAT;	2004/09/20 08:53
			US-PGPUB;	
10	37777	((dia an ahin \$1 an dia) saidh (annia an da ah\$2 an ailia an))	JPO	2004/00/20 09.52
10	31111	((die or chip\$1 or dice) with (semiconduct\$3 or silicon)) same (contact\$1 or pad\$1)	USPAT;	2004/09/20 08:53
		(contactor or pagor)	US-PGPUB; JPO	
14	200755	travers\$3	USPAT;	2004/09/20 09:16
14	200733	Uave1845	USPAT, US-PGPUB;	2004/09/20 09.10
			лоз-гогов, ло	
16	1300	(bus\$2 near2 conduct\$4) same (travers\$3 or cross\$3 or across\$3)	USPAT;	2004/09/20 09:17
10	1300	(busy2 fical2 college (gaversy3 of clossy3 of acrossy3)	US-PGPUB;	2004/09/20 09.17
			DS-гогов,	
17	46	((bus\$2 near2 conduct\$4) same (travers\$3 or cross\$3 or across\$3)) same	USPAT;	2004/09/20 09:18
1'	-	(die or chip\$1 or dice)	US-PGPUB;	2007107120 07.10
		((are or embat or eree)	лоз-гогов, лео	
18	2	test\$3 and (((die or chip\$1 or dice) with (semiconduct\$3 or silicon))	USPAT;	2004/09/20 09:19
"	_	same (contact\$1 or pad\$1)) and ((wafer\$1 near2 level) or wafer-level)	US-PGPUB;	2004/03/20 03:13
		and (((bus\$2 near2 conduct\$4) same (travers\$3 or cross\$3 or across\$3))	JPO	
		same (die or chip\$1 or dice))	"	
19	44	(((bus\$2 near2 conduct\$4) same (travers\$3 or cross\$3 or across\$3))	USPAT;	2004/09/20 09:19
		same (die or chip\$1 or dice)) not (test\$3 and (((die or chip\$1 or dice)	US-PGPUB;	200 1/03/20 03:13
		with (semiconduct\$3 or silicon)) same (contact\$1 or pad\$1)) and	ло ЛРО	
		((wafer\$1 near2 level) or wafer-level) and (((bus\$2 near2 conduct\$4)	0	
		same (travers\$3 or cross\$3 or across\$3)) same (die or chip\$1 or dice)))		
20	2	test\$3 and ((wafer\$1 near2 level) or wafer-level) and redistribut\$3 and	USPAT;	2004/09/20 09:20
	_	((bus\$2 near2 conduct\$4) same (travers\$3 or cross\$3 or across\$3)) and	US-PGPUB;	2001107120 07.20
		(((die or chip\$1 or dice) with (semiconduct\$3 or silicon)) same	ло ЛРО	
		((contact\$1 or pad\$1))		
	L	(continuent of paramity)	l	L